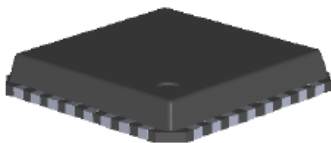
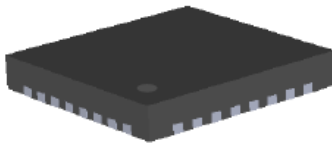


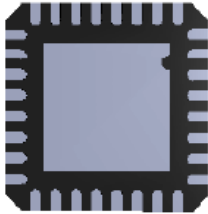
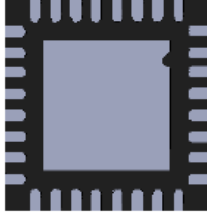


## Bill of Materials:

Package	Body Size	Material	Amkor	Stats ChiPAC	Remarks
LFCSP	7x7 mm 6x6 mm 5x5 mm	Die Attach	Ablestik 8290	Ablestik 3230	
		Wire	1.0 mil	1.0 mil	Same
		Mold Compound	Sumitomo G700	Sumitomo G770	
		Leadframe	C194	C194	Same
	4x4 mm 3x3 mm	Die Attach	Ablestik 8290	Ablestik 8290	Same
		Wire	1.0 mil	1.0 mil	Same
		Mold Compound	Sumitomo G700	Sumitomo G770	
		Leadframe	C194	C194	Same



## Package Outline (Punch and Sawn LFCSP)

COMPARISON	CURRENT	NEW	REMARKS
Package	Punch	Sawn	
Figure			Punch has flange edges. Sawn has sharp square edges.
Thickness	0.85 mm (Nom.) 	0.75 mm (Nom.) 	Sawn is Thinner
Foot Print			Lead width and length dimensions and tolerances are the same.





**Qualification Data for LFCSP Devices at StatsChippac-Malaysia**

<b>QUALIFICATION RESULTS 48-LFCSP</b>			
<b>TEST</b>	<b>CONDITIONS</b>	<b>SAMPLE SIZE (LOT/QTY)</b>	<b>RESULTS</b>
High Temperature Storage (HTS)	JESD22-A103, 150°C, 1000 hours	1 x 45	Pass
Temperature Cycle*	JESD22-A104, -65°C to +150°C, 2 cycle per hour, 500 cycles	3 x 77	Pass
Biased HAST *	JESD22-A110, 130°C, 85% RH, 96hrs	3 x 77	Pass
Autoclave*	JESD22-A102, 121°C, 100% RH, 96hrs	3 x 77	Pass
Solder Heat Resistance (SHR)*	ADI-0049	3 x 15	Pass
Electrostatic Discharge (ESD) Field Induced Charged Device Model (FICDM)	JESD22-C101, >500V	1 x 3	Pass

<b>QUALIFICATION RESULTS 20-LFCSP</b>			
<b>TEST</b>	<b>CONDITIONS</b>	<b>SAMPLE SIZE (LOT/QTY)</b>	<b>RESULTS</b>
High Temperature Storage (HTS)	JESD22-A103, 150°C, 1000 hours	1 x 40	Pass
Temperature Cycle*	JESD22-A104, -65°C to +150°C, 2 cycle per hour, 500 cycles	3 x 77	Pass
Biased HAST *	JESD22-A110, 130°C, 85% RH, 96hrs	3 x 77	Pass
Autoclave*	JESD22-A102, 121°C, 100% RH, 96hrs	3 x 77	Pass
Solder Heat Resistance (SHR)*	ADI-0049	3 x 15	Pass
Electrostatic Discharge (ESD) Field Induced Charged Device Model (FICDM)	JESD22-C101, >1500V	1 x 3	Pass

\*Preconditioned per JEDEC/IPC J-STD-020 MSL 3